

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BOK KYU CHOI	08/25/2008
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si
City:	Kyongki-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12207549
CORRESPONDENCE DATA	
Fax Number:	(312)427-6663
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3124271300
Email:	nicholas.kubacki@ladas.net
Correspondent Name:	RICHARD J. STREIT
Address Line 1:	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.
Address Line 4:	CHICAGO, ILLINOIS 60604
ATTORNEY DOCKET NUMBER:	CU-6804 WWP/NK
NAME OF SUBMITTER:	Woochoon W. Park
Total Attachments: 2 source=cu6804assign#page1.tif source=cu6804assign#page2.tif	

CH \$40.00 12207549

UNITED STATES OF AMERICA

ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:

Name : Bok Kyu CHOI

Address : 103-108, Godam Dormitory, 72-1, Godam-dong, Icheon-si, Gyeonggi-do, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

SEMICONDUCTOR PACKAGE, STACKED SEMICONDUCTOR PACKAGE HAVING THE SAME,
AND A METHOD FOR SELECTING ONE SEMICONDUCTOR CHIP IN A STACKED
SEMICONDUCTOR PACKAGE

(TITLE)

and which is found in *(check one applicable item below)*

U.S. patent application executed on even date herewith

U.S. Application Serial No. _____ filed on _____

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits

PATENT

REEL: 021506 FRAME: 0168

required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

August 25, 2008

Date

Bok Kyu Choi

INVENTOR: Bok Kyu CHOI

0699P/1